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Under the Paperwork Reduction Act of 1995, no pareons are required to respond to a collection of information unless it contains a valid OMB control number. Substitute for form 1449A/PTO Complete if Known INFORMATION DISCLOSURE **Application Number** 10/634174 STATEMENT BY APPLICANT (Use as many sheets as necessary) August 5, 2003 **Filing Date** First Named Inventor Forbes, Leonard <del>2826</del> 2823 **Group Art Unit** Tran, Tan J. García **Examiner Name** TATE TRADEMA Attorney Docket No: 1303.102US1 Sheet 1 of 7

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	First Named Inventor	Forbes, Leonard	
	Group Art Unit	<del>-2826</del> 2823	
	Examiner Name	Iran, Tan J. García	
Sheet 2 of 7	Attorney Docket No: 1	303.102US1	

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Use as many sheets as necessary)	Filing Date	August 5, 2003		
	First Named Inventor	Forbes, Leonard		
	Group Art Unit	<del>2826</del> 28 23		
	Examiner Name	Tran, Tan J. Garaa		
Sheet 3 of 7	Attorney Docket No: 1303.102US1			

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	First Named Inventor	Forbes, Leonard		
	<b>Group Art Unit</b>	2826 2823		
	Examiner Name	Tran, Tan J. García		
Sheet 4 of 7	Attorney Docket No: 1	303.102US1		

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	Group Art Unit	- <del>2826</del> 2823	
	Examiner Name	Tran, Tan J. García	
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	<b>Application Number</b>	10/634174
	Filing Date	August 5, 2003
	First Named Inventor	Forbes, Leonard
	Group Art Unit	<del>2826</del> 28 23
	Examiner Name	Tran, Tan J. Garas
Sheet 7 of 7	Attorney Docket No: 1303.102US1	

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EXAMINER DATE CONSIDERED July 22 voly

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